Document Title

256Kx 4 High Speed Static RAM(5V Operating), Evolutionary Pin Out. Operated at Commercial Temperature Range.

Revision History

<u>Rev. No.</u>	<u>History</u>			Draft Data	<u>Remark</u>
Rev. 0.0	Initial release with De	sign Target.		Jan. 18th, 1995	Design Target
Rev. 1.0	Release to Preliminar 1.1. Replace Design T	•	Apr. 22th, 1995	Preliminary	
Rev. 2.0	Release to final Data 2.1. Delete Preliminar			Feb. 29th, 1996	Final
Rev. 3.0	Update D.C and A.C p 3.1. Update D.C parar Items Icc Isb Isb1 3.2. Update A.C parar Items tcw tAW twP1(OE=H) tow	neters Previous spec. (15/17/20ns part) 190/180/170mA 30mA 10mA	Updated spec. (15/17/20ns part) 145/145/140mA 25mA 8mA Updated spec. (15/17/20ns part) 10/11/12ns 10/11/12ns 10/11/12ns 7/8/9ns	Jul. 16th, 1996	Final
Rev. 4.0	Update D.C and A.C p 4.1. Update D.C and <i>i</i> Items Icc tow 4.2. Add the test cond	A.C parameters A.C parameters. Previous spec. (15/17/20ns part) 145/145/140mA 3/4/5ns ition for VoH1 with Vcc=5V m to define twP as "(Timir	Updated spec. (15/17/20ns part) 125/125/120mA 3/3/3ns ±5% at 25°C	Jun. 2nd, 1997	Final
Rev. 5.0	5.1. Delete 17ns Part			Feb. 25th, 1998	Final

The attached data sheets are prepared and approved by SAMSUNG Electronics. SAMSUNG Electronics CO., LTD. reserve the right to change the specifications. SAMSUNG Electronics will evaluate and reply to your requests and questions on the parameters of this device. If you have any questions, please contact the SAMSUNG branch office near your office, call or contact Headquarters.



256K x 4 Bit (with OE)High-Speed CMOS Static RAM

FEATURES

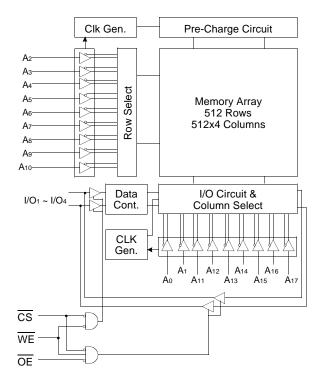
- Fast Access Time 15, 20ns(Max.)
- Low Power Dissipation Standby (TTL) : 25mA(Max.) (CMOS) : 8mA(Max.)
 Operating KM641001A - 15 : 125mA(Max.) KM641001A - 20 : 120mA(Max.)
- Single 5.0V±10% Power Supply
- TTL Compatible Inputs and Outputs
- I/O Compatible with 3.3V Device
- Fully Static Operation
- No Clock or Refresh required
- Three State Outputs
- Standard Pin Configuration
 KM641001AJ : 28-SOJ-400A

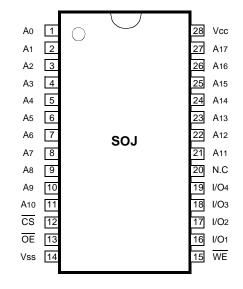
GENERAL DESCRIPTION

The KM641001A is a 1,048,576-bit high-speed Static Random Access Memory organized as 262,144 words by 4 bits. The KM641001A uses 4 common input and output lines and has an output enable pin which operates faster than address access time at read cycle. The device is fabricated using SAMSUNG's advanced CMOS process and designed for high-speed circuit technology. It is particularly well suited for use in high-density high-speed system applications. The KM641001A is packaged in a 400 mil 28-pin plastic SOJ.

PIN CONFIGURATION(Top View)

FUNCTIONAL BLOCK DIAGRAM





PIN FUNCTION

Pin Name	Pin Function
A0 - A17	Address Inputs
WE	Write Enable
CS	Chip Select
OE	Output Enable
I/O1 ~ I/O4	Data Inputs/Outputs
Vcc	Power(+5.0V)
Vss	Ground
N.C	No Connection



ABSOLUTE MAXIMUM RATINGS*

Parameter	Symbol	Rating	Unit
Voltage on Any Pin Relative to Vss	Vin, Vout	-0.5 to 7.0	V
Voltage on Vcc Supply Relative to Vss	Vcc	-0.5 to 7.0	V
Power Dissipation	PD	1.0	W
Storage Temperature	Тѕтс	-65 to 150	°C
Operating Temperature	ТА	0 to 70	°C

* Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS(TA=0 to 70°C)

Parameter	Symbol	Min	Тур	Max	Unit
Supply Voltage	Vcc	4.5	5.0	5.5	V
Ground	Vss	0	0	0	V
Input High Voltage	Vін	2.2	-	Vcc + 0.5**	V
Input Low Voltage	VIL	-0.5*	-	0.8	V

* VIL(Min)=-2.0V a.c(Pulse Width \leq 10ns) for I \leq 20mA

** VIH(Max)=Vcc + 2.0V a.c (Pulse Width \leq 10ns) for I \leq 20mA

DC AND OPERATING CHARACTERISTICS(TA=0 to 70°C, Vcc=5.0V±10%, unless otherwise specified)

Parameter	Symbol	Test Conditions		Min	Max	Unit
Input Leakage Current	ILI	VIN = Vss to Vcc		-2	2	μA
Output Leakage Current	Ilo	CS=VIH or OE=VIH or WE=VIL Vo⊔T=Vss to Vcc		-2	2	μΑ
Operating Current			15ns	-	125	mA
CS=VIL, VIN = VI		\overline{CS} =VIL, VIN = VIH or VIL, IOUT=0mA	20ns	-	120	
Standby Current	Isb	Min. Cycle, CS=Vн		-	25	mA
	ISB1	f=0MHz, CS≥Vcc-0.2V, VIN≥Vcc-0.2V or VIN≤ 0.2V		-	8	mA
Output Low Voltage Level	Vol	Iol=8mA		-	0.4	V
Output High Voltage Level	Vон	IOH=-4mA		2.4	-	V
	VOH1*	Іон1=-0.1mA		-	3.95	V

* Vcc=5.0V, Temp =25°C

CAPACITANCE*(TA=25°C, f=1.0MHz)

Item	Symbol	Test Conditions	MIN	Max	Unit
Input/Output Capacitance	Ci/O	VI/O=0V	-	8	pF
Input Capacitance	CIN	Vin=0V	-	6	pF

 * NOTE : Capacitance is sampled and not 100% tested.



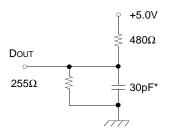
AC CHARACTERISTICS(TA=0 to 70°C, Vcc=5.0V±10%, unless otherwise noted.)

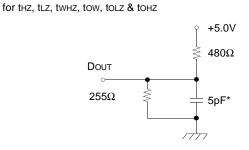
TEST CONDITIONS

Parameter	Value
Input Pulse Levels	0V to 3V
Input Rise and Fall Times	3ns
Input and Output timing Reference Levels	1.5V
Output Loads	See below

Output Loads(B)

Output Loads(A)





* Including Scope and Jig Capacitance

READ CYCLE

Deremeter	Symbol	KM641	001A-15	KM641001A-20		Unit
Parameter	Symbol	Min	Max	Min	Мах	Unit
Read Cycle Time	tRC	15	-	20	-	ns
Address Access Time	taa	-	15	-	20	ns
Chip Select to Output	tco	-	15	-	20	ns
Output Enable to Valid Output	tOE	-	8	-	10	ns
Chip Enable to Low-Z Output	tLZ	3	-	3	-	ns
Output Enable to Low-Z Output	tolz	0	-	0	-	ns
Chip Disable to High-Z Output	tHZ	0	6	0	8	ns
Output Disable to High-Z Output	tohz	0	6	0	8	ns
Output Hold from Address Change	tон	3	-	3	-	ns
Chip Selection to Power Up Time	tPU	0	-	0	-	ns
Chip Selection to Power DownTime	tPD	-	15	-	20	ns

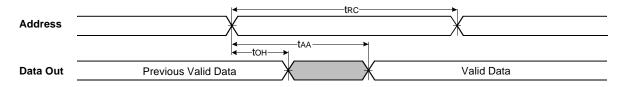


WRITE CYCLE

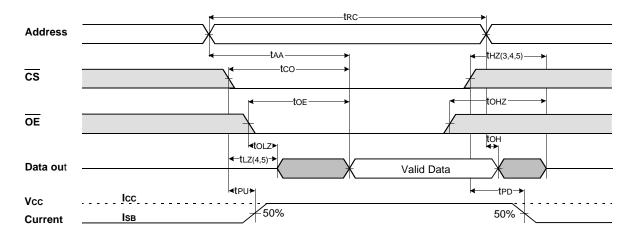
Devenuetor	Cumula al	KM641	001A-15	KM641001A-20		l Incit
Parameter	Symbol	Min	Max	Min	Max	Unit
Write Cycle Time	twc	15	-	20	-	ns
Chip Select to End of Write	tcw	10	-	12	-	ns
Address Set-up Time	tas	0	-	0	-	ns
Address Valid to End of Write	taw	10	-	12	-	ns
Write Pulse Width(OE High)	tWP	10	-	12	-	ns
Write Pulse Width(OE Low)	tWP1	15	-	20	-	ns
Write Recovery Time	twR	0	-	0	-	ns
Write to Output High-Z	twnz	0	8	0	10	ns
Data to Write Time Overlap	tDW	7	-	9	-	ns
Data Hold from Write Time	tDH	0	-	0	-	ns
End Write to Output Low-Z	tow	3	-	3	-	ns

TIMMING DIAGRAMS

TIMING WAVEFORM OF READ CYCLE(1) (Address Controlled, CS=OE=VIL, WE=VIH)



TIMING WAVEFORM OF READ CYCLE(2) (WE=VIH)

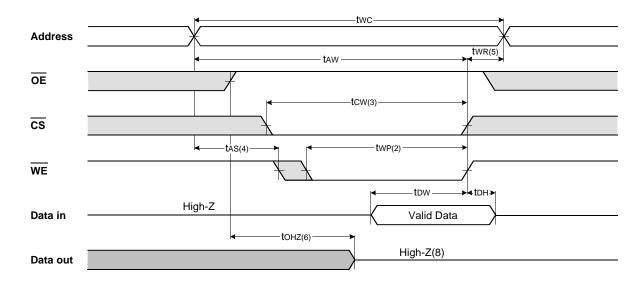




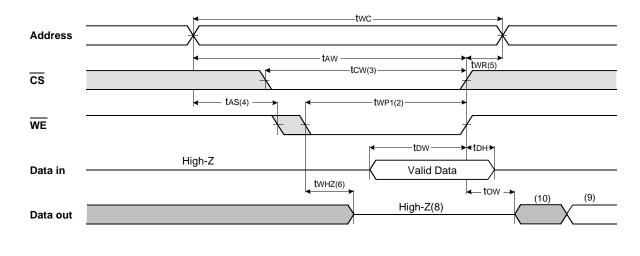
NOTES(READ CYCLE)

- 1. WE is high for read cycle.
- 2. All read cycle timing is referenced from the last valid address to the first transition address.
- 3. tHz and tOHz are defined as the time at which the outputs achieve the open circuit condition and are not referenced to VOH or VoL levels.
- 4. At any given temperature and voltage condition, tHz(Max.) is less than tLz(Min.) both for a given device and from device to device.
- 5. Transition is measured ±200mV from steady state voltage with Load(B). This parameter is sampled and not 100% tested.
- 6. Device is continuously selected with CS=VIL.
- 7. Address valid prior to coincident with $\overline{\text{CS}}$ transition low.
- 8. For common I/O applications, minimization or elimination of bus contention conditions is necessary during read and write cycle.

TIMING WAVEFORM OF WRITE CYCLE(1) (OE = Clock)

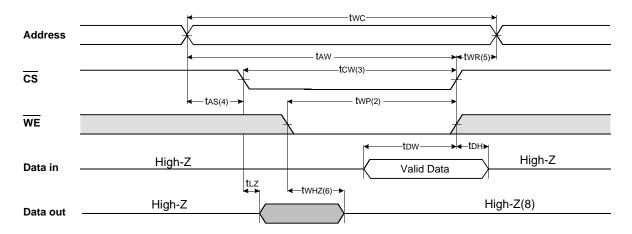


TIMING WAVEFORM OF WRITE CYCLE(2) (OE=Low Fixed)





TIMING WAVEFORM OF WRITE CYCLE(3) (CS=Controlled)



NOTES(WRITE CYCLE)

- 1. All write cycle timing is referenced from the last valid address to the first transition address.
- 2. A write occurs during the overlap of a low CS and WE. A write begins at the latest transition CS going low and WE going low; A write ends at the earliest transition CS going high or WE going high. twp is measured from the beginning of write to the end of write.
- 3. tcw is measured from the later of \overline{CS} going low to end of write.
- 4. tas is measured from the address valid to the beginning of write.
- 5. twe is measured from the end of write to the address change. twe applied in case a write ends as \overline{CS} or \overline{WE} going high.
- 6. If OE, CS and WE are in the Read Mode during this period, the I/O pins are in the output low-Z state. Inputs of opposite phase of the output must not be applied because bus contention can occur.
- 7. For common I/O applications, minimization or elimination of bus contention conditions is necessary during read and write cycle.
- 8. If CS goes low simultaneously with WE going or after WE going low, the outputs remain high impedance state.
- 9. Dout is the read data of the new address.
- 10.When CS is low : I/O pins are in the output state. The input signals in the opposite phase leading to the output should not be applied.

CS	WE	OE	Mode	I/O Pin	Supply Current
н	Х	Х*	Not Select	High-Z	ISB, ISB1
L	Н	Н	Output Disable	High-Z	Icc
L	Н	L	Read	Dout	Icc
L	L	Х	Write	DIN	Icc

FUNCTIONAL DESCRIPTION

* NOTE : X means Don't Care.



PACKAGE DIMENSIONS

